

Indium8.9ATG Pb-Free Solder Paste



The following cleaning testing has been conducted in ZESTRON® technical centers. Prior to recommendation by Indium, the board cleanliness level has been assessed successfully in accordance to the following standards:

- IPC 610
- J-STD 001
- IPC-TM 650

Flux Removal in an Aqueous Cleaning Process:

Inline Cleaning Process					
Cleaning Agent	Conc.	Conveyer belt speed	Cleaning temperature	Rinsing agent	Drying
VIGON® A 201	15%	1.1 feet / min.	150°F / 65°C	DI-water	Circulating air

Inline cleaning processes are usually recommended for high throughput. With a non-foaming cleaning agent such as VIGON® A 201, the high-pressure process is a must for versatility and speed.

Batch Cleaning Process					
Cleaning Agent	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
VIGON® A 200+	15%	10 min.	135°F / 57°C	DI-water	Circulating air

Batch cleaning processes are renowned for their small footprint and are mostly recommended for high mix/low volume production.

Ultrasonic Cleaning Process					
Cleaning Agent	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
VIGON® US	15%	10 min.	135°F / 57°C	DI-water	Circulating air

Ultrasonic cleaning processes are most effective with hard substrates such as ceramics. The low surface tension value of VIGON® US makes it ideal to clean underneath BGA's and Flip-Chips.

OVER →

APPLICATION NOTE

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Flux Removal in a Semi-Aqueous Cleaning Process:

Ultrasonic Cleaning Process					
Cleaning Agent	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
ZESTRON® FA ⁺	100%	10 min.	135°F / 57°C	DI-water	Circulating air

Ultrasonic cleaning processes are most effective with hard substrates such as ceramics. ZESTRON® FA⁺'s high bath loading capability, when compared to traditional solvents, ensures an extended bath life and is a very cost effective process.

Solder Paste Removal in an Aqueous Cleaning Process:

Spray in Air and Ultrasonic Cleaning				
Cleaning Agent	Cleaning time	Cleaning temperature	Rinsing agent	Drying
VIGON® SC 200	5 min.	68°F / 20°C	Not required	Circulating air

Automated stencil cleaning processes typically provide reliable and reproducible cleaning results. VIGON® SC 200 is designed to remove unreflowed solder paste as well as adhesive in heated and unheated stencil cleaning systems.

Application recommendations are intended to serve as a guideline only. For additional cleaning process recommendation or to request a free cleaning trial, please contact ZESTRON®:



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